

74F240 • 74F241 • 74F244

Octal Buffers/Line Drivers with 3-STATE Outputs

General Description

The 74F240, 74F241 and 74F244 are octal buffers and line drivers designed to be employed as memory and address drivers, clock drivers and bus-oriented transmitters/receivers which provide improved PC and board density.

Features

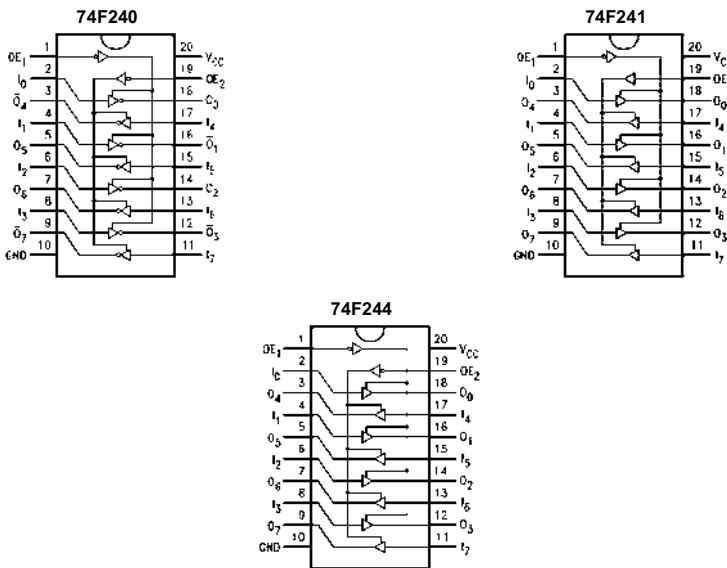
- 3-STATE outputs drive bus lines or buffer memory address registers
- Outputs sink 64 mA (48 mA mil)
- 12 mA source current
- Input clamp diodes limit high-speed termination effects

Ordering Code:

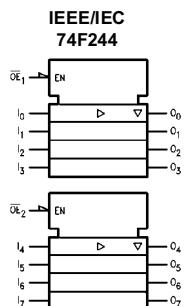
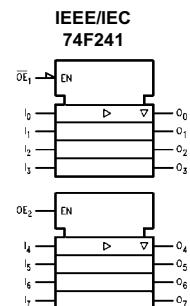
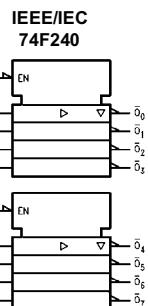
Order Code	Package Number	Package Description
74F240SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F240SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F240PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
74F241SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F241SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F241PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
74F244SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F244MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74F244PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagrams



Logic Symbols



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
\bar{OE}_1 , \bar{OE}_2	3-STATE Output Enable Input (Active LOW)	1.0/1.667	20 μ A/-1 mA
OE_2	3-STATE Output Enable Input (Active HIGH)	1.0/1.667	20 μ A/-1 mA
I_0 - I_7	Inputs (74F240)	1.0/1.667 (Note 1)	20 μ A/-1 mA
I_0 - I_7	Inputs (74F241, 74F244)	1.0/2.667 (Note 1)	20 μ A/-1.6 mA
\bar{O}_0 - \bar{O}_7 , O_0 - O_7	Outputs	600/106.6 (80)	-12 mA/64 mA (48 mA)

Note 1: Worst-case 74F240 enabled; 74F241, 74F244 disabled

Truth Tables

74F240

\bar{OE}_1	D_{1n}	O_{1n}	\bar{OE}_2	D_{2n}	O_{2n}
H	X	Z	H	X	Z
L	H	L	L	H	L
L	L	H	L	L	H

74F244

\bar{OE}_1	D_{1n}	O_{1n}	\bar{OE}_2	D_{2n}	O_{2n}
H	X	Z	H	X	Z
L	H	H	L	H	H
L	L	L	L	L	L

74F241

\bar{OE}_1	D_{1n}	O_{1n}	OE_2	D_{2n}	O_{2n}
H	X	Z	L	X	Z
L	H	H	H	H	H
L	L	L	H	L	L

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

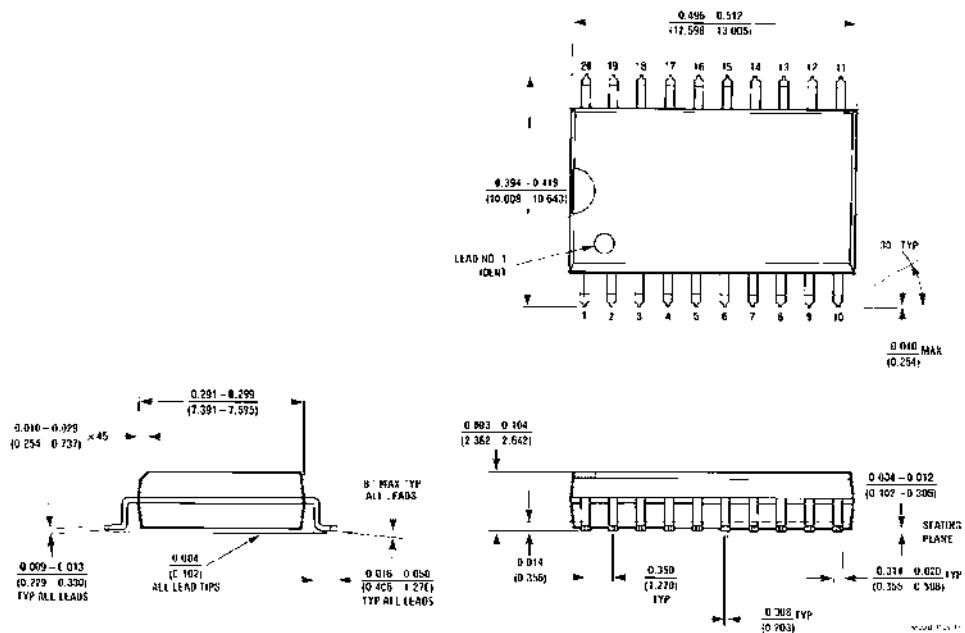
Z = High Impedance

Absolute Maximum Ratings ^(Note 2)		Recommended Operating Conditions					
Storage Temperature	-65°C to +150°C						
Ambient Temperature under Bias	-55°C to +125°C						
Junction Temperature under Bias	-55°C to +150°C						
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V						
Input Voltage (Note 3)	-0.5V to +7.0V						
Input Current (Note 3)	-30 mA to +5.0 mA						
Voltage Applied to Output							
in HIGH State (with V _{CC} = 0V)							
Standard Output	-0.5V to V _{CC}						
3-STATE Output	-0.5V to +5.5V						
Current Applied to Output							
in LOW State (Max)	twice the rated I _{OL} (mA)						
ESD Last Passing Voltage (Min)	4000V						
DC Electrical Characteristics							
Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage		0.8		V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage		-1.2		V	Min	I _{IN} = -18 mA
V _{OH}	Output HIGH Voltage	10% V _{CC}	2.4		V	Min	I _{OH} = -3 mA
		10% V _{CC}	2.0				I _{OH} = -15 mA
		5% V _{CC}	2.7				I _{OH} = -3 mA
V _{OL}	Output LOW Voltage	10% V _{CC}		0.55	V	Min	I _{OL} = 64 mA
I _{IH}	Input HIGH Current			5.0	µA	Max	V _{IN} = 2.7V
I _{BVI}	Input HIGH Current Breakdown Test			7.0	µA	Max	V _{IN} = 7.0V
I _{CEx}	Output HIGH Leakage Current			50	µA	Max	V _{OUT} = V _{CC}
V _{ID}	Input Leakage Test		4.75		V	0.0	I _{ID} = 1.9 µA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current			3.75	µA	0.0	V _{OD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			-1.0 -1.6	mA	Max	V _{IN} = 0.5V (OE ₁ , OE ₂ , OE ₃ , D _n (74F240)) V _{IN} = 0.5V (D _n (74F241, 74F244))
I _{OZH}	Output Leakage Current			50	µA	Max	V _{OUT} = 2.7V
I _{OZL}	Output Leakage Current			-50	µA	Max	V _{OUT} = 0.5V
I _{OS}	Output Short-Circuit Current	-100	-225		mA	Max	V _{OUT} = 0V
I _{ZZ}	Bus Drainage Test		500		µA	0.0V	V _{OUT} = 5.25V
I _{CCH}	Power Supply Current (74F240)	19	29		mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current (74F240)	50	75		mA	Max	V _O = LOW
I _{CCZ}	Power Supply Current (74F240)	42	63		mA	Max	V _O = HIGH Z
I _{CCH}	Power Supply Current (74F241, 74F244)	40	60		mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current (74F241, 74F244)	60	90		mA	Max	V _O = LOW
I _{CCZ}	Power Supply Current (74F241, 74F244)	60	90		mA	Max	V _O = HIGH Z

AC Electrical Characteristics

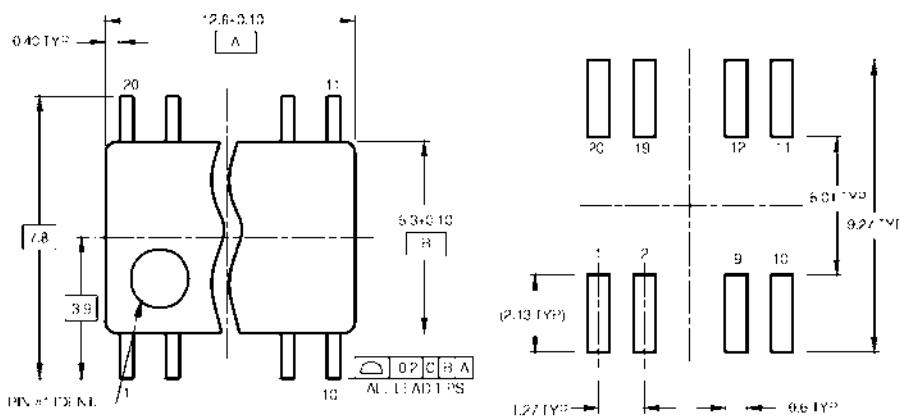
Symbol	Parameter	$T_A = +25^\circ C$ $V_{CC} = +5.0V$ $C_L = 50 pF$			$T_A = -55^\circ C \text{ to } +125^\circ C$ $V_{CC} = 5.0V$ $C_L = 50 pF$		$T_A = 0^\circ C \text{ to } +70^\circ C$ $V_{CC} = 5.0V$ $C_L = 50 pF$		Units
		Min	Typ	Max	Min	Max	Min	Max	
t_{PLH}	Propagation Delay Data to Output (74F240)	3.0 2.0	5.1 3.5	7.0 4.7	3.0 2.0	9.0 6.0	3.0 2.0	8.0 5.7	ns
t_{PZH}	Output Enable Time (74F240)	2.0	3.5	4.7	2.0	6.5	2.0	5.7	
t_{PZL}		4.0	6.9	9.0	4.0	10.5	4.0	10.0	
t_{PHZ}	Output Disable Time (74F240)	2.0	4.0	5.3	2.0	6.5	2.0	6.3	
t_{PLZ}		2.0	6.0	8.0	2.0	12.5	2.0	9.5	
t_{PLH}	Propagation Delay Data to Output (74F241, 74F244)	2.5 2.5	4.0 4.0	5.2 5.2	2.0 2.0	6.5 7.0	2.5 2.5	6.2 6.5	ns
t_{PZH}	Output Enable Time (74F241, 74F244)	2.0	4.3	5.7	2.0	7.0	2.0	6.7	
t_{PZL}		2.0	5.4	7.0	2.0	8.5	2.0	8.0	
t_{PHZ}	Output Disable Time (74F241, 74F244)	2.0	4.5	6.0	2.0	7.0	2.0	7.0	
t_{PLZ}		2.0	4.5	6.0	2.0	7.5	2.0	7.0	

Physical Dimensions inches (millimeters) unless otherwise noted

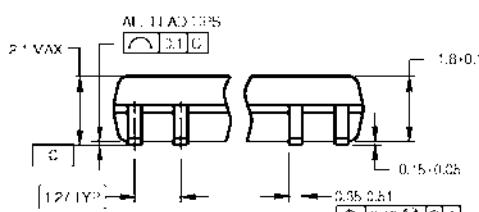


20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M20B

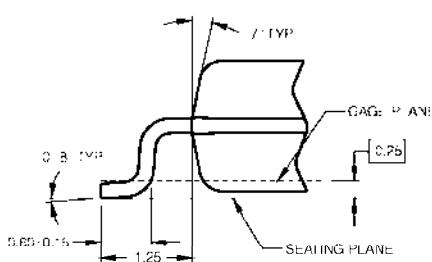
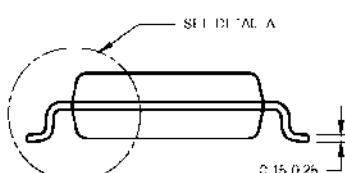
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



J AND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



NOTES

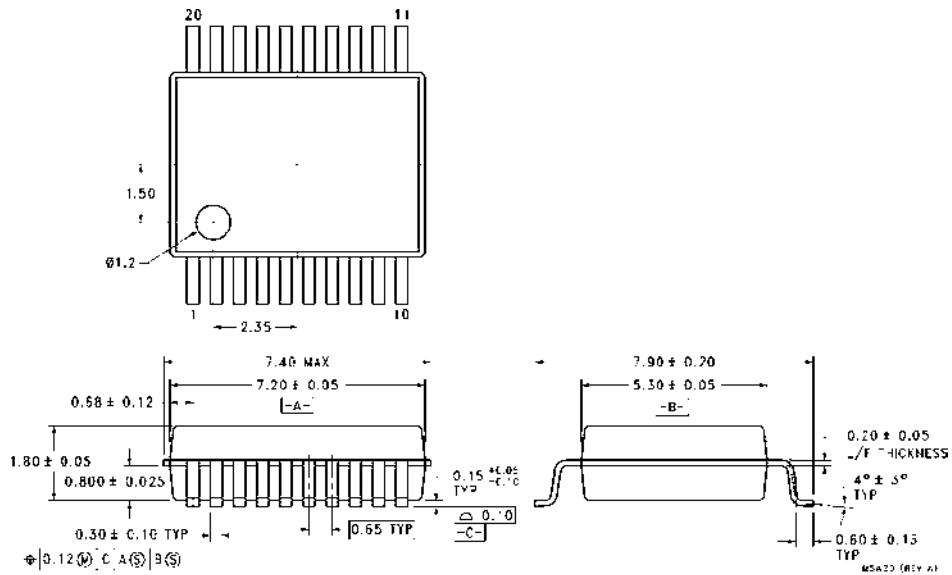
- A. CONFORMS TO JEDEC JESD26 PRECISION.
- B. STABISH DIN 41733 B, 1998.
- C. DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUDING BURRS, VOID FLASH, AND TIE BAR EXHUSIONS.

M20DRevB1

DETAIL A

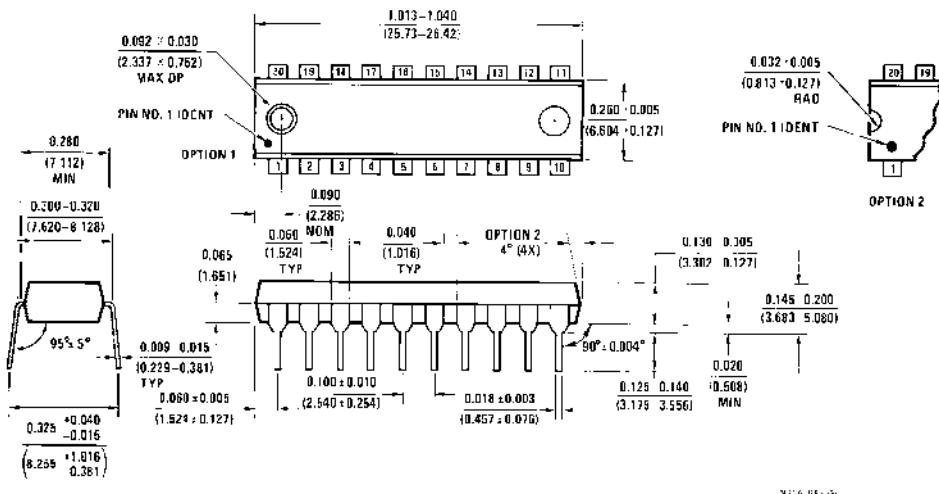
20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
Package Number N20A

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